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Understanding Embedded - FPGAs (Field Programmable Gate Array)

Embedded - FPGAs, or Field Programmable Gate Arrays, are advanced integrated circuits that offer unparalleled flexibility and performance for digital systems. Unlike traditional fixed-function logic devices, FPGAs can be programmed and reprogrammed to execute a wide array of logical operations, enabling customized functionality tailored to specific applications. This reprogrammability allows developers to iterate designs quickly and implement complex functions without the need for custom hardware.

Applications of Embedded - FPGAs

The versatility of Embedded - FPGAs makes them indispensable in numerous fields. In telecommunications.

Details	
Product Status	Obsolete
Number of LABs/CLBs	192
Number of Logic Elements/Cells	1728
Total RAM Bits	73728
Number of I/O	124
Number of Gates	50000
Voltage - Supply	1.14V ~ 1.26V
Mounting Type	Surface Mount
Operating Temperature	0°C ~ 85°C (TJ)
Package / Case	208-BFQFP
Supplier Device Package	208-PQFP (28x28)
Purchase URL	https://www.e-xfl.com/product-detail/xilinx/xc3s50-4pq208c

Table 9: **Differential I/O Standards**

Signal Standard (IOSTANDARD)	V_{CCO} (Volts)		V_{REF} for Inputs (Volts)
	For Outputs	For Inputs	
LDT_25 (ULVDS_25)	2.5	–	–
LVDS_25	2.5	–	–
BLVDS_25	2.5	–	–
LVDSEXT_25	2.5	–	–
LVPECL_25	2.5	–	–
RSDS_25	2.5	–	–
DIFF_HSTL_II_18	1.8	–	–
DIFF_SSTL2_II	2.5	–	–

Notes:

1. See Table 10 for a listing of the differential DCI standards.

The need to supply V_{REF} and V_{CCO} imposes constraints on which standards can be used in the same bank. See The Organization of IOBs into Banks section for additional guidelines concerning the use of the V_{CCO} and V_{REF} lines.

Digitally Controlled Impedance (DCI)

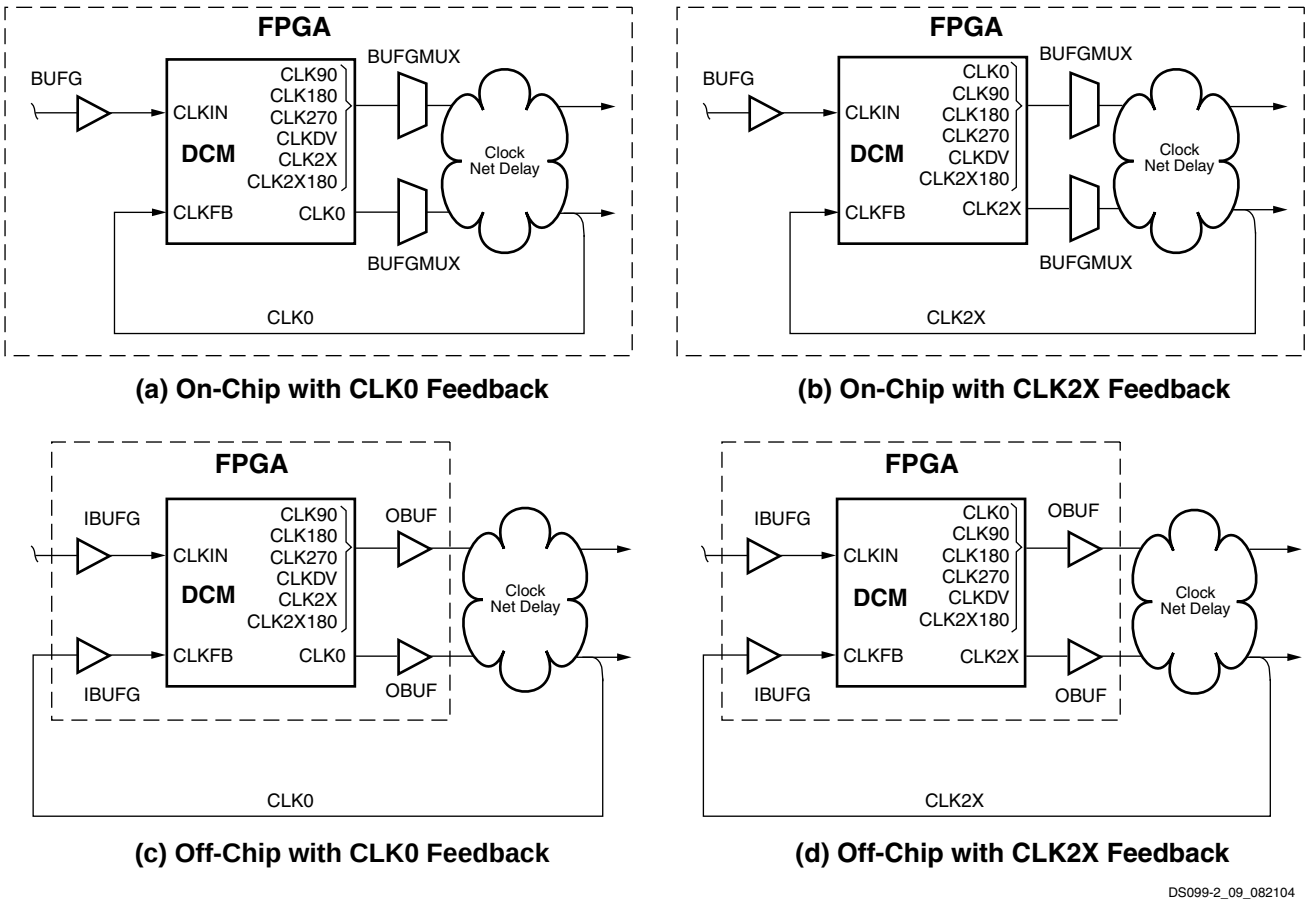
When the round-trip delay of an output signal—i.e., from output to input and back again—exceeds rise and fall times, it is common practice to add termination resistors to the line carrying the signal. These resistors effectively match the impedance of a device's I/O to the characteristic impedance of the transmission line, thereby preventing reflections that adversely affect signal integrity. However, with the high I/O counts supported by modern devices, adding resistors requires significantly more components and board area. Furthermore, for some packages—e.g., ball grid arrays—it may not always be possible to place resistors close to pins.

DCI answers these concerns by providing two kinds of on-chip terminations: Parallel terminations make use of an integrated resistor network. Series terminations result from controlling the impedance of output drivers. DCI actively adjusts both parallel and series terminations to accurately match the characteristic impedance of the transmission line. This adjustment process compensates for differences in I/O impedance that can result from normal variation in the ambient temperature, the supply voltage and the manufacturing process. When the output driver turns off, the series termination, by definition, approaches a very high impedance; in contrast, parallel termination resistors remain at the targeted values.

DCI is available only for certain I/O standards, as listed in Table 10. DCI is selected by applying the appropriate I/O standard extensions to symbols or components. There are five basic ways to configure terminations, as shown in Table 11. The DCI I/O standard determines which of these terminations is put into effect.

HSTL_I_DCI-, HSTL_III_DCI-, and SSTL2_I_DCI-type outputs do not require the VRN and VRP reference resistors. Likewise, LVDCI-type inputs do not require the VRN and VRP reference resistors. In a bank without any DCI I/O or a bank containing non-DCI I/O and purely HSTL_I_DCI- or HSTL_III_DCI-type outputs, or SSTL2_I_DCI-type outputs or LVDCI-type inputs, the associated VRN and VRP pins can be used as general-purpose I/O pins.

The HSLVDCI (High-Speed LVDCI) standard is intended for bidirectional use. The driver is identical to LVDCI, while the input is identical to HSTL. By using a V_{REF}-referenced input, HSLVDCI allows greater input sensitivity at the receiver than when using a single-ended LVCMOS-type receiver.



(a) On-Chip with CLK0 Feedback

(b) On-Chip with CLK2X Feedback

(c) Off-Chip with CLK0 Feedback

(d) Off-Chip with CLK2X Feedback

DS099-2_09_082104

Notes:

1. In the Low Frequency mode, all seven DLL outputs are available. In the High Frequency mode, only the CLK0, CLK180, and CLKDV outputs are available.

Figure 21: **Input Clock, Output Clock, and Feedback Connections for the DLL**

In the on-chip synchronization case (the [a] and [b] sections of Figure 21), it is possible to connect any of the DLL's seven output clock signals through general routing resources to the FPGA's internal registers. Either a Global Clock Buffer (BUFG) or a BUFGMUX affords access to the global clock network. As shown in the [a] section of Figure 21, the feedback loop is created by routing CLK0 (or CLK2X, in the [b] section) to a global clock net, which in turn drives the CLKFB input.

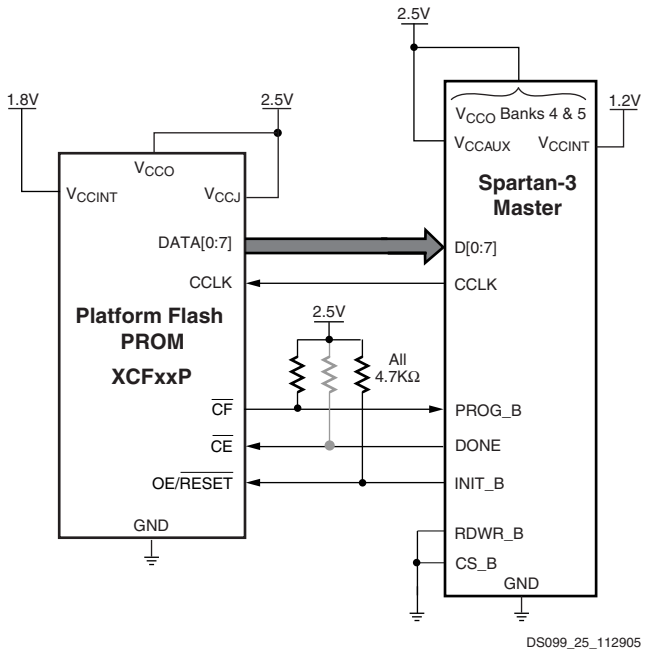
In the off-chip synchronization case (the [c] and [d] sections of Figure 21), CLK0 (or CLK2X) plus any of the DLL's other output clock signals exit the FPGA using output buffers (OBUF) to drive an external clock network plus registers on the board. As shown in the [c] section of Figure 21, the feedback loop is formed by feeding CLK0 (or CLK2X, in the [d] section) back into the FPGA using an IBUFG, which directly accesses the global clock network, or an IBUF. Then, the global clock net is connected directly to the CLKFB input.

DLL Frequency Modes

The DLL supports two distinct operating modes, High Frequency and Low Frequency, with each specified over a different clock frequency range. The DLL_FREQUENCY_MODE attribute chooses between the two modes. When the attribute is set to LOW, the Low Frequency mode permits all seven DLL clock outputs to operate over a low-to-moderate frequency range. When the attribute is set to HIGH, the High Frequency mode allows the CLK0, CLK180 and CLKDV outputs to operate at the highest possible frequencies. The remaining DLL clock outputs are not available for use in High Frequency mode.

Accommodating High Input Frequencies

If the frequency of the CLKIN signal is high such that it exceeds the maximum permitted, divide it down to an acceptable value using the CLKIN_DIVIDE_BY_2 attribute. When this attribute is set to TRUE, the CLKIN frequency is divided by a factor of two just as it enters the DCM.



Notes:

1. There are two ways to use the DONE line. First, one may set the BitGen option DriveDone to "Yes" only for the last FPGA to be configured in the chain shown above (or for the single FPGA as may be the case). This enables the DONE pin to drive High; thus, no pull-up resistor is necessary. DriveDone is set to "No" for the remaining FPGAs in the chain. Second, DriveDone can be set to "No" for all FPGAs. Then all DONE lines are open-drain and require the pull-up resistor shown in grey. In most cases, a value between 3.3KΩ to 4.7KΩ is sufficient. However, when using DONE synchronously with a long chain of FPGAs, cumulative capacitance may necessitate lower resistor values (e.g. down to 330Ω) in order to ensure a rise time within one clock cycle.

Figure 28: **Connection Diagram for Master Parallel Configuration**

Master Parallel Mode

In this mode, the FPGA configures from byte-wide data, and the FPGA supplies the CCLK configuration clock. In Master configuration modes, CCLK behaves as a bidirectional I/O pin. Timing is similar to the Slave Parallel mode except that CCLK is supplied by the FPGA. The device connections are shown in Figure 28.

Boundary-Scan (JTAG) Mode

In Boundary-Scan mode, dedicated pins are used for configuring the FPGA. The configuration is done entirely through the IEEE 1149.1 Test Access Port (TAP). FPGA configuration using the Boundary-Scan mode is compatible with the IEEE Std 1149.1-1993 standard and IEEE Std 1532 for In-System Configurable (ISC) devices.

Configuration through the boundary-scan port is always available, regardless of the selected configuration mode. In some cases, however, the mode pin setting may affect proper programming of the device due to various interactions. For example, if the mode pins are set to Master Serial or Master Parallel mode, and the associated PROM is already programmed with a valid configuration image, then there is potential for configuration interference between the JTAG and PROM data. Selecting the Boundary-Scan mode disables the other modes and is the most reliable mode when programming via JTAG.

Configuration Sequence

The configuration of Spartan-3 devices is a three-stage process that occurs after Power-On Reset or the assertion of PROG_B. POR occurs after the V_{CCINT}, V_{CCAUX}, and V_{CCO} Bank 4 supplies have reached their respective maximum input threshold levels (see Table 29, page 59). After POR, the three-stage process begins.

First, the configuration memory is cleared. Next, configuration data is loaded into the memory, and finally, the logic is activated by a start-up process. A flow diagram for the configuration sequence of the Serial and Parallel modes is shown in Figure 29. The flow diagram for the Boundary-Scan configuration sequence appears in Figure 30.

Revision History

Date	Version No.	Description
04/11/03	1.0	Initial Xilinx release
05/19/03	1.1	Added Block RAM column, DCMs, and multipliers to XC3S50 descriptions.
07/11/03	1.2	Explained the configuration port *Persist* option in Slave Parallel Mode (SelectMAP) section. Updated Figure 8 and Double-Data-Rate Transmission section to indicate that DDR clocking for the XC3S50 is the same as that for all other Spartan-3 devices. Updated description of I/O voltage tolerance in ESD Protection section. In Table 10, changed input termination type for DCI version of the LVCMOS standard to *None*. Added additional flexibility for making DLL connections in Figure 21 and accompanying text. In the Configuration section, inserted an explanation of how to choose power supplies for the configuration interface, including guidelines for achieving 3.3V-tolerance.
08/24/04	1.3	Showed inversion of 3-state signal (Figure 7). Clarified description of pull-up and pull-down resistors (Table 6 and page 13). Added information on operating block RAM with multipliers to page 26. Corrected output buffer name in Figure 21. Corrected description of how DOUT is synchronized to CCLK (page 47).
08/19/05	1.4	Corrected description of WRITE_FIRST and READ_FIRST in Table 13. Added note regarding address setup and hold time requirements whenever a block RAM port is enabled (Table 13). Added information in the maximum length of a Configuration daisy-chain. Added reference to XAPP453 in 3.3V-Tolerant Configuration Interface section. Added information on the STATUS[2] DCM output (Table 23). Added information on CCLK behavior and termination recommendations to Configuration. Added Additional Configuration Details section. Added Powering Spartan-3 FPGAs section. Removed GSR from Figure 31 because its timing is not programmable.
04/03/06	2.0	Updated Figure 7. Updated Figure 14. Updated Table 10. Updated Figure 22. Corrected Platform Flash supply voltage name and value in Figure 26 and Figure 28. Added No Internal Charge Pumps or Free-Running Oscillators. Corrected a few minor typographical errors.
04/26/06	2.1	Added more information on the pull-up resistors that are active during configuration to Configuration. Added information to Boundary-Scan (JTAG) Mode about potential interactions when configuring via JTAG if the mode select pins are set for other than JTAG.
05/25/07	2.2	Added Spartan-3 FPGA Design Documentation. Noted SSTL2_I_DCI 25-Ohm driver in Table 10 and Table 11. Added note that pull-down is active during boundary scan tests.
11/30/07	2.3	Updated links to documentation on xilinx.com.
06/25/08	2.4	Added HSLVDCI to Table 10. Updated formatting and links.
12/04/09	2.5	Updated HSLVDCI description in Digitally Controlled Impedance (DCI). Updated the low-voltage differential signaling V_{CCO} values in Table 10. Noted that the CP132 package is being discontinued in The Organization of IOBs into Banks. Updated rule 4 in Rules Concerning Banks. Added software version requirement in The Fixed Phase Mode.
10/29/12	3.0	Added Notice of Disclaimer. Per XCN07022, updated the discontinued FG1156 and FGG1156 package discussion throughout document. Per XCN08011, updated the discontinued CP132 and CPG132 package discussion throughout document. This product is not recommended for new designs.

Table 28: **Absolute Maximum Ratings *(Cont'd)***

Symbol	Description	Conditions	Min	Max	Units
I_{IK}	Input clamp current per I/O pin	–0.5 V < V_{IN} < (V_{CCO} + 0.5 V)	–	±100	mA
V_{ESD}	Electrostatic Discharge Voltage pins relative to GND	Human body model	–	±2000	V
		Charged device model	–	±500	V
		Machine model	–	±200	V
T_J	Junction temperature		–	125	°C
T_{SOL}	Soldering temperature(4)		–	220	°C
T_{STG}	Storage temperature		–65	150	°C

Notes:

1. Stresses beyond those listed under Absolute Maximum Ratings may cause permanent damage to the device. These are stress ratings only; functional operation of the device at these or any other conditions beyond those listed under the Recommended Operating Conditions is not implied. Exposure to Absolute Maximum Ratings conditions for extended periods of time adversely affects device reliability.
2. All User I/O and Dual-Purpose pins (DIN/D0, D1–D7, CS_B, RDWR_B, BUSY/DOUT, and INIT_B) draw power from the V_{CCO} power rail of the associated bank. Keeping VIN within 500 mV of the associated V_{CCO} rails or ground rail ensures that the internal diode junctions that exist between each of these pins and the V_{CCO} and GND rails do not turn on. Table 32 specifies the V_{CCO} range used to determine the max limit. Input voltages outside the –0.5V to V_{CCO}+0.5V voltage range are permissible provided that the I_{IK} input clamp diode rating is met and no more than 100 pins exceed the range simultaneously. Prolonged exposure to such current may compromise device reliability. A sustained current of 10 mA will not compromise device reliability. See XAPP459, *Eliminating I/O Coupling Effects when Interfacing Large-Swing Single-Ended Signals to User I/O Pins on Spartan-3 Generation FPGAs* for more details. The VIN limits apply to both the DC and AC components of signals. Simple application solutions are available that show how to handle overshoot/undershoot as well as achieve PCI compliance. Refer to the following application notes: XAPP457, *Powering and Configuring Spartan-3 Generation FPGAs in Compliant PCI Applications* and XAPP659, *Virtex®-II Pro / Virtex-II Pro X 3.3V I/O Design Guidelines*.
3. All Dedicated pins (M0–M2, CCLK, PROG_B, DONE, HSWAP_EN, TCK, TDI, TDO, and TMS) draw power from the V_{CCAUX} rail (2.5V). Meeting the V_{IN} max limit ensures that the internal diode junctions that exist between each of these pins and the V_{CCAUX} rail do not turn on. Table 32 specifies the V_{CCAUX} range used to determine the max limit. When V_{CCAUX} is at its maximum recommended operating level (2.625V), V_{IN} max < 3.125V. As long as the V_{IN} max specification is met, oxide stress is not possible. For information concerning the use of 3.3V signals, see the 3.3V-Tolerant Configuration Interface, page 47. See also XAPP459.
4. For soldering guidelines, see UG112, *Device Packaging and Thermal Characteristics* and XAPP427, *Implementation and Solder Reflow Guidelines for Pb-Free Packages*.

Table 29: **Supply Voltage Thresholds for Power-On Reset**

Symbol	Description	Min	Max	Units
V_{CCINTT}	Threshold for the V_{CCINT} supply	0.4	1.0	V
V_{CCAUXT}	Threshold for the V_{CCAUX} supply	0.8	2.0	V
V_{CCO4T}	Threshold for the V_{CCO} Bank 4 supply	0.4	1.0	V

Notes:

1. V_{CCINT}, V_{CCAUX}, and V_{CCO} supplies may be applied in any order. When applying V_{CCINT} power before V_{CCAUX} power, the FPGA may draw a *surplus* current in addition to the quiescent current levels specified in Table 34. Applying V_{CCAUX} eliminates the surplus current. The FPGA does not use any of the surplus current for the power-on process. For this power sequence, make sure that regulators with foldback features will not shut down inadvertently.
2. To ensure successful power-on, V_{CCINT}, V_{CCO} Bank 4, and V_{CCAUX} supplies must rise through their respective threshold-voltage ranges with no dips at any point.
3. If a brown-out condition occurs where V_{CCAUX} or V_{CCINT} drops below the retention voltage indicated in Table 31, then V_{CCAUX} or V_{CCINT} must drop below the minimum power-on reset voltage in order to clear out the device configuration content.

Table 50: **Recommended Number of Simultaneously Switching Outputs per V_{CCO}/GND Pair *(Cont'd)***

Signal Standard (IOSTANDARD)			Package				
			VQ100	TQ144	PQ208	CP132	FT256, FG320, FG456, FG676, FG900, FG1156
LVCMOS33	Slow	2	34	24	24	52	76
		4	17	14	14	26	46
		6	17	11	11	26	27
		8	10	10	10	13	20
		12	9	9	9	13	13
		16	8	8	8	8	10
		24	8	8	8	8	9
	Fast	2	20	20	20	26	44
		4	15	15	15	15	26
		6	11	11	11	13	16
		8	10	10	10	10	12
		12	8	8	8	8	10
		16	8	8	8	8	8
		24	7	7	7	7	7
LVDCI_33			10	10	10	10	10
LVDCI_DV2_33			10	10	10	10	10
HSLVDCI_33			10	10	10	10	10
LVTTL	Slow	2	34	25	25	52	60
		4	17	16	16	26	41
		6	17	15	15	26	29
		8	12	12	12	13	22
		12	10	10	10	13	13
		16	10	10	10	10	11
		24	8	8	8	8	9
	Fast	2	20	20	20	26	34
		4	13	13	13	13	20
		6	11	11	11	13	15
		8	10	10	10	10	12
		12	9	9	9	9	10
		16	8	8	8	8	9
		24	7	7	7	7	7

Digital Clock Manager (DCM) Timing

For specification purposes, the DCM consists of three key components: the Delay-Locked Loop (DLL), the Digital Frequency Synthesizer (DFS), and the Phase Shifter (PS).

Aspects of DLL operation play a role in all DCM applications. All such applications inevitably use the CLKIN and the CLKFB inputs connected to either the CLK0 or the CLK2X feedback, respectively. Thus, specifications in the DLL tables (Table 58 and Table 59) apply to any application that only employs the DLL component. When the DFS and/or the PS components are used together with the DLL, then the specifications listed in the DFS and PS tables (Table 60 through Table 63) supersede any corresponding ones in the DLL tables. DLL specifications that do not change with the addition of DFS or PS functions are presented in Table 58 and Table 59.

Period jitter and cycle-cycle jitter are two (of many) different ways of characterizing clock jitter. Both specifications describe statistical variation from a mean value.

Period jitter is the worst-case deviation from the average clock period of all clock cycles in the collection of clock periods sampled (usually from 100,000 to more than a million samples for specification purposes). In a histogram of period jitter, the mean value is the clock period.

Cycle-cycle jitter is the worst-case difference in clock period between adjacent clock cycles in the collection of clock periods sampled. In a histogram of cycle-cycle jitter, the mean value is zero.

Delay-Locked Loop (DLL)

Table 58: **Recommended Operating Conditions for the DLL**

Symbol		Description	Frequency Mode/ F_{CLKIN} Range	Speed Grade				Units
				-5		-4		
				Min	Max	Min	Max	
Input Frequency Ranges								
F_{CLKIN}	CLKIN_FREQ_DLL_LF	Frequency for the CLKIN input	Low	18(2)	167(3)	18(2)	167(3)	MHz
	CLKIN_FREQ_DLL_HF		High	48	280(3)	48	280(3)(4)	MHz
Input Pulse Requirements								
CLKIN_PULSE		CLKIN pulse width as a percentage of the CLKIN period	$F_{CLKIN} \leq 100$ MHz	40%	60%	40%	60%	-
			$F_{CLKIN} > 100$ MHz	45%	55%	45%	55%	-
Input Clock Jitter Tolerance and Delay Path Variation(5)								
CLKIN_CYC_JITT_DLL_LF		Cycle-to-cycle jitter at the CLKIN input	Low	–	±300	–	±300	ps
CLKIN_CYC_JITT_DLL_HF			High	–	±150	–	±150	ps
CLKIN_PER_JITT_DLL_LF		Period jitter at the CLKIN input	All	–	±1	–	±1	ns
CLKIN_PER_JITT_DLL_HF				–		–		
CLKFB_DELAY_VAR_EXT		Allowable variation of off-chip feedback delay from the DCM output to the CLKFB input	All	–	±1	–	±1	ns

Notes:

1. DLL specifications apply when any of the DLL outputs (CLK0, CLK90, CLK180, CLK270, CLK2X, CLK2X180, or CLKDV) are in use.
2. The DFS, when operating independently of the DLL, supports lower F_{CLKIN} frequencies. See Table 60.
3. The CLKIN_DIVIDE_BY_2 attribute can be used to increase the effective input frequency range up to F_{BUFG}. When set to TRUE, CLKIN_DIVIDE_BY_2 divides the incoming clock frequency by two as it enters the DCM.
4. Industrial temperature range devices have additional requirements for continuous clocking, as specified in Table 64.
5. CLKIN input jitter beyond these limits may cause the DCM to lose lock. See UG331 for more details.

Table 59: **Switching Characteristics for the DLL**

Symbol	Description	Frequency Mode / FCLKIN Range	Device	Speed Grade				Units
				-5		-4		
				Min	Max	Min	Max	
Output Frequency Ranges								
CLKOUT_FREQ_1X_LF	Frequency for the CLK0, CLK90, CLK180, and CLK270 outputs	Low	All	18	167	18	167	MHz
CLKOUT_FREQ_1X_HF	Frequency for the CLK0 and CLK180 outputs	High		48	280	48	280	MHz
CLKOUT_FREQ_2X_LF(3)	Frequency for the CLK2X and CLK2X180 outputs	Low		36	334	36	334	MHz
CLKOUT_FREQ_DV_LF	Frequency for the CLKDV output	Low		1.125	110	1.125	110	MHz
CLKOUT_FREQ_DV_HF		High		3	185	3	185	MHz
Output Clock Jitter(4)								
CLKOUT_PER_JITT_0	Period jitter at the CLK0 output	All	All	–	±100	–	±100	ps
CLKOUT_PER_JITT_90	Period jitter at the CLK90 output			–	±150	–	±150	ps
CLKOUT_PER_JITT_180	Period jitter at the CLK180 output			–	±150	–	±150	ps
CLKOUT_PER_JITT_270	Period jitter at the CLK270 output			–	±150	–	±150	ps
CLKOUT_PER_JITT_2X	Period jitter at the CLK2X and CLK2X180 outputs			–	±200	–	±200	ps
CLKOUT_PER_JITT_DV1	Period jitter at the CLKDV output when performing integer division			–	±150	–	±150	ps
CLKOUT_PER_JITT_DV2	Period jitter at the CLKDV output when performing non-integer division			–	±300	–	±300	ps
Duty Cycle								
CLKOUT_DUTY_CYCLE_DLL(5)	Duty cycle variation for the CLK0, CLK90, CLK180, CLK270, CLK2X, CLK2X180, and CLKDV outputs	All	XC3S50	–	±150	–	±150	ps
			XC3S200	–	±150	–	±150	ps
			XC3S400	–	±250	–	±250	ps
			XC3S1000	–	±400	–	±400	ps
			XC3S1500	–	±400	–	±400	ps
			XC3S2000	–	±400	–	±400	ps
			XC3S4000	–	±400	–	±400	ps
			XC3S5000	–	±400	–	±400	ps
Phase Alignment								
CLKIN_CLKFB_PHASE	Phase offset between the CLKIN and CLKFB inputs	All	All	–	±150	–	±150	ps
CLKOUT_PHASE	Phase offset between any two DLL outputs (except CLK2X and CLK0)			–	±140	–	±140	ps
	Phase offset between the CLK2X and CLK0 outputs			–	±250	–	±250	ps

Table 71: **Dual-Purpose Pins Used in Master or Slave Serial Mode**

Pin Name	Direction	Description
DIN	Input	**Serial Data Input:** During the Master or Slave Serial configuration modes, DIN is the serial configuration data input, and all data is synchronized to the rising CCLK edge. After configuration, this pin is available as a user I/O. This signal is located in Bank 4 and its output voltage determined by VCCO_4. The BitGen option ***Persist*** permits this pin to retain its configuration function in the User mode.
DOUT	Output	**Serial Data Output:** In a multi-FPGA design where all the FPGAs use serial mode, connect the DOUT output of one FPGA—in either Master or Slave Serial mode—to the DIN input of the next FPGA—in Slave Serial mode—so that configuration data passes from one to the next, in daisy-chain fashion. This "daisy chain" permits sequential configuration of multiple FPGAs. This signal is located in Bank 4 and its output voltage determined by VCCO_4. The BitGen option ***Persist*** permits this pin to retain its configuration function in the User mode.
INIT_B	Bidirectional (open-drain)	**Initializing Configuration Memory/Configuration Error:** Just after power is applied, the FPGA produces a Low-to-High transition on this pin indicating that initialization (*i.e.*, clearing) of the configuration memory has finished. Before entering the User mode, this pin functions as an open-drain output, which requires a pull-up resistor in order to produce a High logic level. In a multi-FPGA design, tie (wire AND) the INIT_B pins from all FPGAs together so that the common node transitions High only after all of the FPGAs have been successfully initialized. Externally holding this pin Low beyond the initialization phase delays the start of configuration. This action stalls the FPGA at the configuration step just before the mode select pins are sampled. During configuration, the FPGA indicates the occurrence of a data (i.e., CRC) error by asserting INIT_B Low. This signal is located in Bank 4 and its output voltage determined by VCCO_4. The BitGen option ***Persist*** permits this pin to retain its configuration function in the User mode.

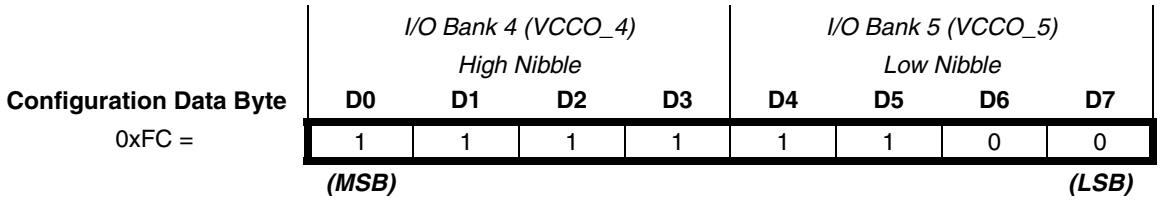


Figure 41: **Configuration Data Byte Mapping to D0-D7 Bits**

Parallel Configuration Modes (SelectMAP)

This section describes the dual-purpose configuration pins used during the Master and Slave Parallel configuration modes, sometimes also called the SelectMAP modes. In both Master and Slave Parallel configuration modes, D0-D7 form the byte-wide configuration data input. See Table 75 for Mode Select pin settings required for Parallel modes.

As shown in Figure 41, D0 is the most-significant bit while D7 is the least-significant bit. Bits D0-D3 form the high nibble of the byte and bits D4-D7 form the low nibble.

In the Parallel configuration modes, both the VCCO_4 and VCCO_5 voltage supplies are required and must both equal the voltage of the attached configuration device, typically either 2.5V or 3.3V.

Assert Low both the chip-select pin, CS_B, and the read/write control pin, RDWR_B, to write the configuration data byte presented on the D0-D7 pins to the FPGA on a rising-edge of the configuration clock, CCLK. The order of CS_B and RDWR_B does not matter, although RDWR_B must be asserted throughout the configuration process. If RDWR_B is de-asserted during configuration, the FPGA aborts the configuration operation.

After configuration, these pins are available as general-purpose user I/O. However, the SelectMAP configuration interface is optionally available for debugging and dynamic reconfiguration. To use these SelectMAP pins after configuration, set the Persist bitstream generation option.

The Readback debugging option, for example, requires the Persist bitstream generation option. During Readback mode, assert CS_B Low, along with RDWR_B High, to read a configuration data byte from the FPGA to the D0-D7 bus on a rising CCLK edge. During Readback mode, D0-D7 are output pins.

In all the cases, the configuration data and control signals are synchronized to the rising edge of the CCLK clock signal.

The 1% precision impedance-matching resistor attached to the VRN_# pin controls the pull-down impedance of NMOS transistor in the input or output buffer. Consequently, the VRN_# pin must connect to VCCO. The 'N' character in "VRN" indicates that this pin controls the I/O buffer's NMOS transistor impedance. The VRN_# pin is only used for split termination.

Each VRN or VRP reference input requires its own resistor. A single resistor cannot be shared between VRN or VRP pins associated with different banks.

During configuration, these pins behave exactly like user-I/O pins. The associated DCI behavior is not active or valid until after configuration completes.

Also see Digitally Controlled Impedance (DCI), page 16.

DCI Termination Types

If the I/O in an I/O bank do not use the DCI feature, then no external resistors are required and both the VRP_# and VRN_# pins are available for user I/O, as shown in section [a] of Figure 42.

If the I/O standards within the associated I/O bank require single termination—such as GTL_DCI, GTLP_DCI, or HSTL_III_DCI—then only the VRP_# signal connects to a 1% precision impedance-matching resistor, as shown in section [b] of Figure 42. A resistor is not required for the VRN_# pin.

Finally, if the I/O standards with the associated I/O bank require split termination—such as HSTL_I_DCI, SSTL2_I_DCI, SSTL2_II_DCI, or LVDS_25_DCI and LVDSEXT_25_DCI receivers—then both the VRP_# and VRN_# pins connect to separate 1% precision impedance-matching resistors, as shown in section [c] of Figure 42. Neither pin is available for user I/O.

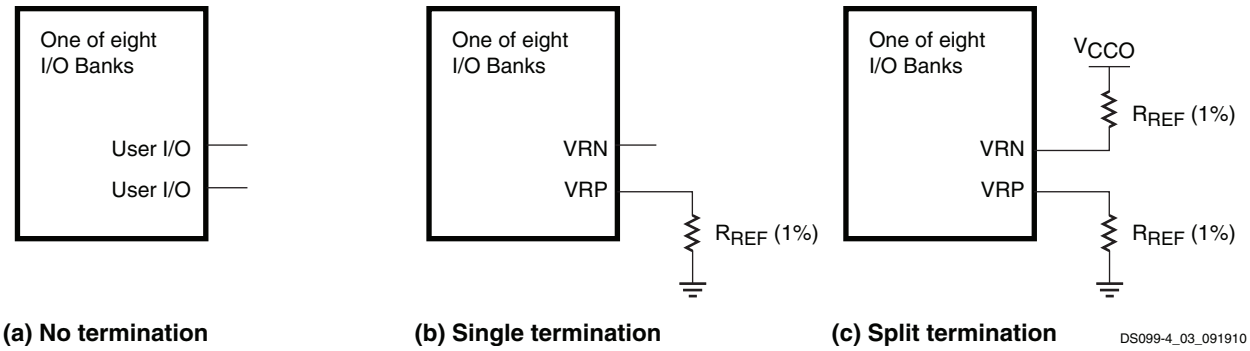


Figure 42: **DCI Termination Types**

GCLK: Global Clock Buffer Inputs or General-Purpose I/O Pins

These pins are user-I/O pins unless they specifically connect to one of the eight low-skew global clock buffers on the device, specified using the IBUFG primitive.

There are eight GCLK pins per device and two each appear in the top-edge banks, Bank 0 and 1, and the bottom-edge banks, Banks 4 and 5. See Figure 40 for a picture of bank labeling.

During configuration, these pins behave exactly like user-I/O pins.

Also see Global Clock Network, page 42.

CONFIG: Dedicated Configuration Pins

The dedicated configuration pins control the configuration process and are not available as user-I/O pins. Every package has seven dedicated configuration pins. All CONFIG-type pins are powered by the +2.5V VCCAUX supply.

Also see Configuration, page 46.

CCLK: Configuration Clock

The configuration clock signal on this pin synchronizes the reading or writing of configuration data. The CCLK pin is an input-only pin for the Slave Serial and Slave Parallel configuration modes. In the Master Serial and Master Parallel configuration modes, the FPGA drives the CCLK pin and CCLK should be treated as a full bidirectional I/O pin for signal integrity analysis.

Although the CCLK frequency is relatively low, Spartan-3 FPGA output edge rates are fast. Any potential signal integrity problems on the CCLK board trace can cause FPGA configuration to fail. Therefore, pay careful attention to the CCLK signal integrity on the printed circuit board. Signal integrity simulation with IBIS is recommended. For all configuration modes except JTAG, consider the signal integrity at every CCLK trace destination, including the FPGA's CCLK pin. For more details on CCLK design considerations, see Chapter 2 of UG332, *Spartan-3 Generation Configuration User Guide*.

During configuration, the CCLK pin has a pull-up resistor to VCCAUX, regardless of the HSWAP_EN pin. After configuration, the CCLK pin is pulled High to VCCAUX by default as defined by the ***CclkPin*** bitstream selection, although this behavior is programmable. Any clocks applied to CCLK after configuration are ignored unless the bitstream option ***Persist*** is set to ***Yes***, which retains the configuration interface. ***Persist*** is set to ***No*** by default. However, if ***Persist*** is set to ***Yes***, then all clock edges are potentially active events, depending on the other configuration control signals.

The bitstream generator option ***ConfigRate*** determines the frequency of the internally-generated CCLK oscillator required for the Master configuration modes. The actual frequency is approximate due to the characteristics of the silicon oscillator and varies by up to 50% over the temperature and voltage range. By default, CCLK operates at approximately 6 MHz. Via the ***ConfigRate*** option, the oscillator frequency is set at approximately 3, 6, 12, 25, or 50 MHz. At power-on, CCLK always starts operation at its lowest frequency. The device does not start operating at the higher frequency until the ConfigRate control bits are loaded during the configuration process.

PROG_B: Program/Configure Device

This asynchronous pin initiates the configuration or re-configuration processes. A Low-going pulse resets the configuration logic, initializing the configuration memory. This initialization process cannot finish until PROG_B returns High. Asserting PROG_B Low for an extended period delays the configuration process. At power-up, there is always a pull-up resistor to VCCAUX on this pin, regardless of the HSWAP_EN input. After configuration, the bitstream generator option ***ProgPin*** determines whether or not the pull-up resistor is present. By default, the ***ProgPin*** option retains the pull-up resistor.

After configuration, hold the PROG_B input High. Any Low-going pulse on PROG_B lasting 300 ns or longer restarts the configuration process.

Table 73: **PROG_B Operation**

PROG_B Input	Response
Power-up	Automatically initiates configuration process.
Low-going pulse 	Initiate (re-)configuration process and continue to completion.
Extended Low	Initiate (re-)configuration process and stall process at step where configuration memory is cleared. Process is stalled until PROG_B returns High.
1	If the configuration process is started, continue to completion. If configuration process is complete, stay in User mode.

DONE: Configuration Done, Delay Start-Up Sequence

The FPGA produces a Low-to-High transition on this pin indicating that the configuration process is complete. The bitstream generator option ***DriveDone*** determines whether this pin functions as a totem-pole output that can drive High or as an open-drain output. If configured as an open-drain output—which is the default behavior—then a pull-up resistor is required to produce a High logic level. There is a bitstream option that provides an internal pull-up resistor, otherwise an external pull-up resistor is required.

The open-drain option permits the DONE lines of multiple FPGAs to be tied together, so that the common node transitions High only after all of the FPGAs have completed configuration. Externally holding the open-drain DONE pin Low delays the start-up sequence, which marks the transition to user mode.

Once the FPGA enters User mode after completing configuration, the DONE pin no longer drives the DONE pin Low. The bitstream generator option DonePin determines whether or not a pull-up resistor is present on the DONE pin to pull the pin to VCCAUX. If the pull-up resistor is eliminated, then the DONE pin must be pulled High using an external pull-up resistor or one of the FPGAs in the design must actively drive the DONE pin High via the DriveDone bitstream generator option.

The bitstream generator option DriveDone causes the FPGA to actively drive the DONE output High after configuration. This option should only be used in single-FPGA designs or on the last FPGA in a multi-FPGA daisy-chain.

By default, the bitstream generator software retains the pull-up resistor and does not actively drive the DONE pin as highlighted in Table 74, which shows the interaction of these bitstream options in single- and multi-FPGA designs.

Table 74: **DonePin and DriveDone Bitstream Option Interaction**

DonePin	DriveDone	Single- or Multi-FPGA Design	Comments
Pullnone	No	Single	External pull-up resistor, with value between 330Ω to 3.3kΩ, required on DONE.
Pullnone	No	Multi	External pull-up resistor, with value between 330Ω to 3.3kΩ, required on common node connecting to all DONE pins.
Pullnone	Yes	Single	OK, no external requirements.
Pullnone	Yes	Multi	DriveDone on last device in daisy-chain only. No external requirements.
Pullup	No	Single	OK, but pull-up on DONE pin has slow rise time. May require 330Ω pull-up resistor for high CCLK frequencies.
Pullup	No	Multi	External pull-up resistor, with value between 330Ω to 3.3kΩ, required on common node connecting to all DONE pins.
Pullup	Yes	Single	OK, no external requirements.
Pullup	Yes	Multi	DriveDone on last device in daisy-chain only. No external requirements.

M2, M1, M0: Configuration Mode Selection

The M2, M1, and M0 inputs select the FPGA configuration mode, as described in Table 75. The logic levels applied to the mode pins are sampled on the rising edge of INIT_B.

Table 75: **Spartan-3 FPGA Mode Select Settings**

Configuration Mode	M2	M1	M0
Master Serial	0	0	0
Slave Serial	1	1	1
Master Parallel	0	1	1
Slave Parallel	1	1	0
JTAG	1	0	1
Reserved	0	0	1
Reserved	0	1	0
Reserved	1	0	0
After Configuration	X	X	X

Notes:

1. X = don't care, either 0 or 1.

Before and during configuration, the mode pins have an internal pull-up resistor to VCCAUX, regardless of the HSWAP_EN pin. If the mode pins are unconnected, then the FPGA defaults to the Slave Serial configuration mode. After configuration successfully completes, any levels applied to these input are ignored. Furthermore, the bitstream generator options M0Pin, M1Pin, and M2Pin determines whether a pull-up resistor, pull-down resistor, or no resistor is present on its respective mode pin, M0, M1, or M2.

Table 93: **PQ208 Package Pinout *(Cont'd)***

Bank	XC3S50 Pin Name	XC3S200, XC3S400 Pin Names	PQ208 Pin Number	Type
3	IO_L20P_3	IO_L20P_3	P114	I/O
3	IO_L21N_3	IO_L21N_3	P117	I/O
3	IO_L21P_3	IO_L21P_3	P116	I/O
3	IO_L22N_3	IO_L22N_3	P120	I/O
3	IO_L22P_3	IO_L22P_3	P119	I/O
3	IO_L23N_3	IO_L23N_3	P123	I/O
3	IO_L23P_3/VREF_3	IO_L23P_3/VREF_3	P122	VREF
3	IO_L24N_3	IO_L24N_3	P125	I/O
3	IO_L24P_3	IO_L24P_3	P124	I/O
3	N.C. (◆)	IO_L39N_3	P128	I/O
3	N.C. (◆)	IO_L39P_3	P126	I/O
3	IO_L40N_3/VREF_3	IO_L40N_3/VREF_3	P131	VREF
3	IO_L40P_3	IO_L40P_3	P130	I/O
3	VCCO_3	VCCO_3	P110	VCCO
3	VCCO_3	VCCO_3	P127	VCCO
4	IO	IO	P93	I/O
4	N.C. (◆)	IO	P97	I/O
4	IO/VREF_4	IO/VREF_4	P85	VREF
4	N.C. (◆)	IO/VREF_4	P96	VREF
4	IO/VREF_4	IO/VREF_4	P102	VREF
4	IO_L01N_4/VRP_4	IO_L01N_4/VRP_4	P101	DCI
4	IO_L01P_4/VRN_4	IO_L01P_4/VRN_4	P100	DCI
4	IO_L25N_4	IO_L25N_4	P95	I/O
4	IO_L25P_4	IO_L25P_4	P94	I/O
4	IO_L27N_4/DIN/D0	IO_L27N_4/DIN/D0	P92	DUAL
4	IO_L27P_4/D1	IO_L27P_4/D1	P90	DUAL
4	IO_L30N_4/D2	IO_L30N_4/D2	P87	DUAL
4	IO_L30P_4/D3	IO_L30P_4/D3	P86	DUAL
4	IO_L31N_4/INIT_B	IO_L31N_4/INIT_B	P83	DUAL
4	IO_L31P_4/DOUT/BUSY	IO_L31P_4/DOUT/BUSY	P81	DUAL
4	IO_L32N_4/GCLK1	IO_L32N_4/GCLK1	P80	GCLK
4	IO_L32P_4/GCLK0	IO_L32P_4/GCLK0	P79	GCLK
4	VCCO_4	VCCO_4	P84	VCCO
4	VCCO_4	VCCO_4	P98	VCCO
5	IO	IO	P63	I/O
5	IO	IO	P71	I/O
5	IO/VREF_5	IO/VREF_5	P78	VREF
5	IO_L01N_5/RDWR_B	IO_L01N_5/RDWR_B	P58	DUAL
5	IO_L01P_5/CS_B	IO_L01P_5/CS_B	P57	DUAL
5	IO_L10N_5/VRP_5	IO_L10N_5/VRP_5	P62	DCI

Right Half of Package (Top View)

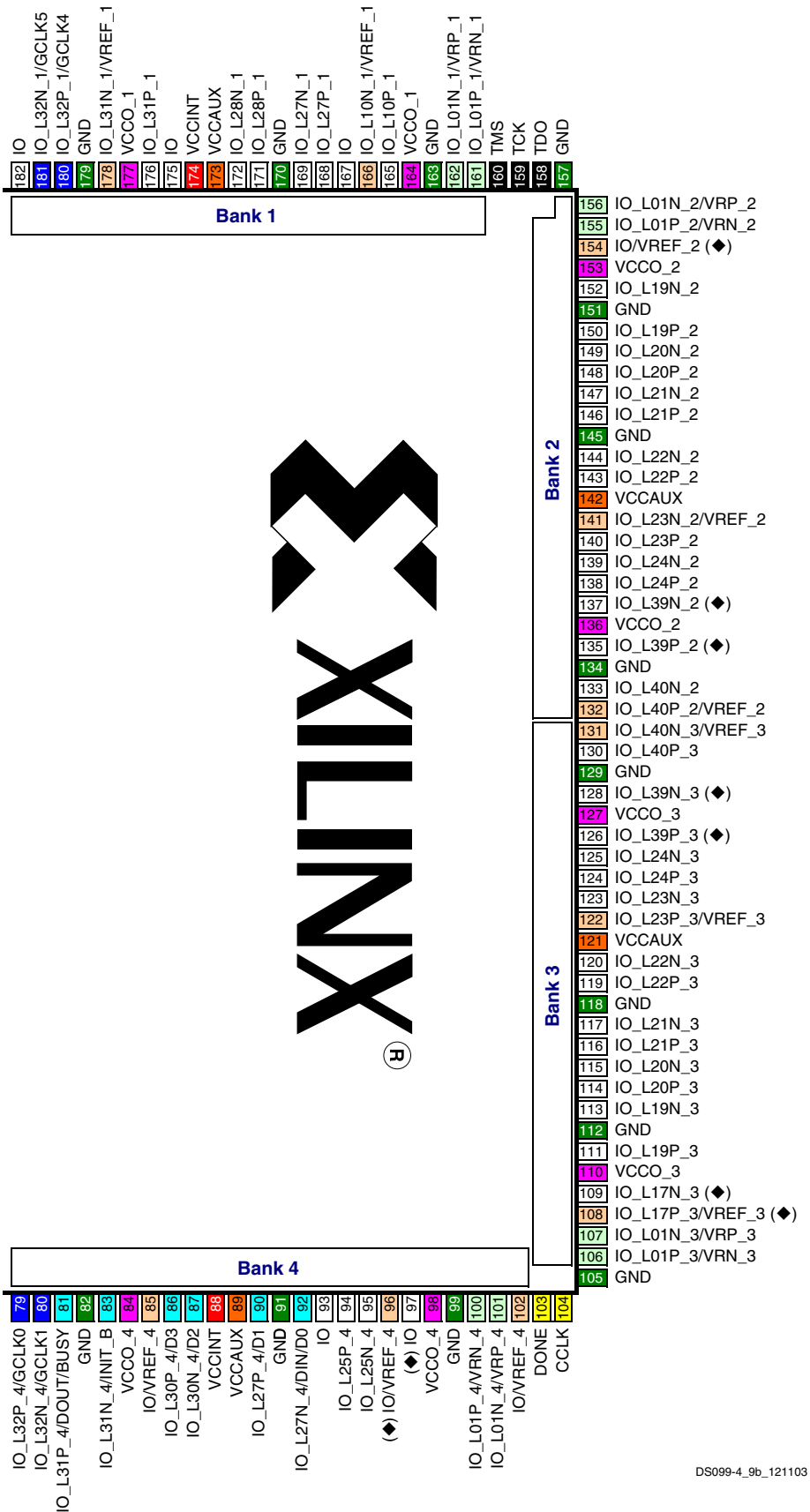


Figure 48: PQ208 Package Footprint (Top View) Continued

Table 100: **FG456 Package Pinout *(Cont'd)***

Bank	3S400 Pin Name	3S1000, 3S1500, 3S2000 Pin Name	FG456 Pin Number	Type
5	IO_L27N_5/VREF_5	IO_L27N_5/VREF_5	W9	VREF
5	IO_L27P_5	IO_L27P_5	V9	I/O
5	IO_L28N_5/D6	IO_L28N_5/D6	AB9	DUAL
5	IO_L28P_5/D7	IO_L28P_5/D7	AA9	DUAL
5	IO_L29N_5	IO_L29N_5	Y10	I/O
5	IO_L29P_5/VREF_5	IO_L29P_5/VREF_5	W10	VREF
5	IO_L30N_5	IO_L30N_5	AB10	I/O
5	IO_L30P_5	IO_L30P_5	AA10	I/O
5	IO_L31N_5/D4	IO_L31N_5/D4	W11	DUAL
5	IO_L31P_5/D5	IO_L31P_5/D5	V11	DUAL
5	IO_L32N_5/GCLK3	IO_L32N_5/GCLK3	AA11	GCLK
5	IO_L32P_5/GCLK2	IO_L32P_5/GCLK2	Y11	GCLK
5	VCCO_5	VCCO_5	T9	VCCO
5	VCCO_5	VCCO_5	T10	VCCO
5	VCCO_5	VCCO_5	T11	VCCO
5	VCCO_5	VCCO_5	U8	VCCO
5	VCCO_5	VCCO_5	Y8	VCCO
6	IO	IO	Y1	I/O
6	IO_L01N_6/VRP_6	IO_L01N_6/VRP_6	Y3	DCI
6	IO_L01P_6/VRN_6	IO_L01P_6/VRN_6	Y2	DCI
6	IO_L16N_6	IO_L16N_6	W4	I/O
6	IO_L16P_6	IO_L16P_6	W3	I/O
6	IO_L17N_6	IO_L17N_6	W2	I/O
6	IO_L17P_6/VREF_6	IO_L17P_6/VREF_6	W1	VREF
6	IO_L19N_6	IO_L19N_6	V5	I/O
6	IO_L19P_6	IO_L19P_6	U5	I/O
6	IO_L20N_6	IO_L20N_6	V4	I/O
6	IO_L20P_6	IO_L20P_6	V3	I/O
6	IO_L21N_6	IO_L21N_6	V2	I/O
6	IO_L21P_6	IO_L21P_6	V1	I/O
6	IO_L22N_6	IO_L22N_6	T6	I/O
6	IO_L22P_6	IO_L22P_6	T5	I/O
6	IO_L23N_6	IO_L23N_6	U4	I/O
6	IO_L23P_6	IO_L23P_6	T4	I/O
6	IO_L24N_6/VREF_6	IO_L24N_6/VREF_6	U3	VREF
6	IO_L24P_6	IO_L24P_6	U2	I/O
6	N.C. (◆)	IO_L26N_6	T3	I/O
6	N.C. (◆)	IO_L26P_6	R4	I/O
6	IO_L27N_6	IO_L27N_6	T2	I/O
6	IO_L27P_6	IO_L27P_6	T1	I/O

FG456 Footprint

Left Half of FG456 Package (Top View)

XC3S400 (264 max. user I/O)

196 **I/O:** Unrestricted, general-purpose user I/O

32 **VREF:** User I/O or input voltage reference for bank

69 **N.C.:** Unconnected pins for XC3S400 (◆)

XC3S1000, XC3S1500, XC3S2000 (333 max user I/O)

261 **I/O:** Unrestricted, general-purpose user I/O

36 **VREF:** User I/O or input voltage reference for bank

0 **N.C.:** No unconnected pins in this package

All devices

12 **DUAL:** Configuration pin, then possible user I/O

8 **GCLK:** User I/O or global clock buffer input

16 **DCI:** User I/O or reference resistor input for bank

7 **CONFIG:** Dedicated configuration pins

4 **JTAG:** Dedicated JTAG port pins

12 **VCCINT:** Internal core voltage supply (+1.2V)

40 **VCCO:** Output voltage supply for bank

8 **VCCAUX:** Auxiliary voltage supply (+2.5V)

52 **GND:** Ground

	Bank 0										
	1	2	3	4	5	6	7	8	9	10	11
A	GND	PROG_B	IO VREF_0	I/O L01P_0 VRN_0	I/O L09P_0	VCCAUX	I/O L19P_0 ◆	I/O L24P_0	I/O L27P_0	I/O	I/O L32P_0 GCLK6
B	TDI	GND	HSWAP_EN	I/O L01N_0 VRP_0	I/O L09N_0	I/O L15P_0	I/O L19N_0 ◆	I/O L24N_0	I/O L27N_0	I/O L29P_0	I/O L32N_0 GCLK7
C	I/O L16P_7 VREF_7	I/O	I/O L01N_7 VRP_7	I/O L01P_7 VRN_7	I/O L06P_0	I/O L15N_0	IO VREF_0	VCCO_0	GND	I/O L29N_0	I/O L31P_0 VREF_0
D	I/O L16N_7	I/O L19P_7	I/O L19N_7 VREF_7	I/O L17P_7	I/O L06N_0	I/O L10P_0	I/O L16P_0	I/O L22P_0 ◆	I/O	I/O	I/O L31N_0
E	I/O L21N_7	I/O L21P_7	I/O L20P_7	I/O L17N_7	IO VREF_0 ◆	I/O L10N_0	I/O L16N_0	I/O L22N_0 ◆	I/O L25P_0	I/O L28P_0	I/O L30P_0
F	VCCAUX	I/O L23N_7	I/O L23P_7	I/O L20N_7	I/O L22P_7	I/O	IO VREF_0	VCCO_0	I/O L25N_0	I/O L28N_0	I/O L30N_0
G	I/O L27N_7	I/O L27P_7 VREF_7	I/O L26N_7 ◆	I/O L26P_7 ◆	I/O L24P_7	I/O L22N_7	VCCINT	VCCINT	VCCO_0	VCCO_0	VCCO_0
H	I/O L28N_7 ◆	I/O L28P_7 ◆	VCCO_7	I/O L29P_7 ◆	I/O L24N_7	VCCO_7	VCCINT				
J	I/O L32N_7 ◆	I/O L32P_7 ◆	GND	I/O L29N_7 ◆	I/O L31N_7 ◆	I/O L31P_7 ◆	VCCO_7		GND	GND	GND
K	I/O L35N_7	I/O L35P_7	I/O L34N_7	I/O L34P_7	I/O L33N_7 ◆	I/O L33P_7 ◆	VCCO_7		GND	GND	GND
L	I/O L40N_7 VREF_7	I/O L40P_7	I/O L39N_7	I/O L39P_7	I/O L38N_7	I/O L38P_7	VCCO_7		GND	GND	GND
M	I/O L40P_6 VREF_6	I/O L40N_6	I/O L39P_6	I/O L39N_6	I/O L38P_6	I/O L38N_6	VCCO_6		GND	GND	GND
N	I/O L35P_6	I/O L35N_6	I/O L34P_6	I/O L34N_6 VREF_6	I/O L33P_6 ◆	I/O L33N_6 ◆	VCCO_6		GND	GND	GND
P	I/O L32P_6 ◆	I/O L32N_6 ◆	GND	I/O L31P_6 ◆	I/O L31N_6 ◆	I/O L28P_6 ◆	VCCO_6		GND	GND	GND
R	I/O L29P_6 ◆	I/O L29N_6 ◆	VCCO_6	I/O L26P_6 ◆	I/O L28N_6 ◆	VCCO_6	VCCINT				
T	I/O L27P_6	I/O L27N_6	I/O L26N_6 ◆	I/O L23P_6	I/O L22P_6	I/O L22N_6	VCCINT	VCCINT	VCCO_5	VCCO_5	VCCO_5
U	VCCAUX	I/O L24P_6	I/O L24N_6 VREF_6	I/O L23N_6	I/O L19P_6	IO VREF_5	I/O	VCCO_5	I/O ◆	I/O	I/O
V	I/O L21P_6	I/O L21N_6	I/O L20P_6	I/O L20N_6	I/O L19N_6	I/O L15P_5	I/O	I/O L24P_5	I/O L27P_5	I/O	I/O L31P_5 D5
W	I/O L17P_6 VREF_6	I/O L17N_6	I/O L16P_6	I/O L16N_6	I/O L09P_5	I/O L15N_5	I/O L19P_5 VREF_5 ◆	I/O L24N_5	I/O L27N_5 VREF_5	I/O L29P_5 VREF_5	I/O L31N_5 D4
Y	I/O	I/O L01P_6 VRN_6	I/O L01N_6 VRP_6	I/O L01N_5 RDWR_B	I/O L09N_5	I/O L16P_5	I/O L19N_5 ◆	VCCO_5	GND	I/O L29N_5	I/O L32P_5 GCLK2
AA	M1	GND	I/O L01P_5 CS_B	I/O L06P_5	I/O L10P_5 VRN_5	I/O L16N_5	I/O L22P_5 ◆	I/O L25P_5	I/O L28P_5 D7	I/O L30P_5	I/O L32N_5 GCLK3
AB	GND	M0	M2	I/O L06N_5	I/O L10N_5 VRP_5	VCCAUX	I/O L22N_5 ◆	I/O L25N_5	I/O L28N_5 D6	I/O L30N_5	IO VREF_5

Bank 7 (rows G–L) · Bank 6 (rows M–T) · Bank 5 (columns 7–11)

DS099-4_11a_030203

Figure 51: **FG456 Package Footprint (Top View)**

Table 103: **FG676 Package Pinout *(Cont'd)***

Bank	XC3S1000 Pin Name	XC3S1500 Pin Name	XC3S2000 Pin Name	XC3S4000 Pin Name	XC3S5000 Pin Name	FG676 Pin Number	Type
N/A	VCCINT	VCCINT	VCCINT	VCCINT	VCCINT	U17	VCCINT
N/A	VCCINT	VCCINT	VCCINT	VCCINT	VCCINT	U18	VCCINT
N/A	VCCINT	VCCINT	VCCINT	VCCINT	VCCINT	V9	VCCINT
N/A	VCCINT	VCCINT	VCCINT	VCCINT	VCCINT	V10	VCCINT
N/A	VCCINT	VCCINT	VCCINT	VCCINT	VCCINT	V17	VCCINT
N/A	VCCINT	VCCINT	VCCINT	VCCINT	VCCINT	V18	VCCINT
N/A	VCCINT	VCCINT	VCCINT	VCCINT	VCCINT	W8	VCCINT
N/A	VCCINT	VCCINT	VCCINT	VCCINT	VCCINT	W19	VCCINT
VCC AUX	CCLK	CCLK	CCLK	CCLK	CCLK	AD26	CONFIG
VCC AUX	DONE	DONE	DONE	DONE	DONE	AC24	CONFIG
VCC AUX	HSWAP_EN	HSWAP_EN	HSWAP_EN	HSWAP_EN	HSWAP_EN	C2	CONFIG
VCC AUX	M0	M0	M0	M0	M0	AE3	CONFIG
VCC AUX	M1	M1	M1	M1	M1	AC3	CONFIG
VCC AUX	M2	M2	M2	M2	M2	AF3	CONFIG
VCC AUX	PROG_B	PROG_B	PROG_B	PROG_B	PROG_B	D3	CONFIG
VCC AUX	TCK	TCK	TCK	TCK	TCK	B24	JTAG
VCC AUX	TDI	TDI	TDI	TDI	TDI	C1	JTAG
VCC AUX	TDO	TDO	TDO	TDO	TDO	D24	JTAG
VCC AUX	TMS	TMS	TMS	TMS	TMS	A24	JTAG

Notes:
1. XC3S1500 balls D25 and F25 are not VREF pins although they are designated as such. If a design uses an IOSTANDARD requiring VREF in bank 2 then apply the workaround in Answer Record 20519.
2. XC3S4000 is pin compatible with XC3S2000 but uses alternate differential pair labeling on six package balls (H20, H21, H22, H23, H24, J21).
3. XC3S5000 is pin compatible with XC3S4000 but uses alternate differential pair functionality on fifteen package balls (A3, A8, B8, B18, C4, C8, C18, D8, D18, E8, E18, H23, H24, AB9, and AC9).

Table 107: **FG900 Package Pinout *(Cont'd)***

Bank	XC3S2000 Pin Name	XC3S4000, XC3S5000 Pin Name	FG900 Pin Number	Type
2	IO_L28N_2	IO_L28N_2	M26	I/O
2	IO_L28P_2	IO_L28P_2	N25	I/O
2	IO_L29N_2	IO_L29N_2	N26	I/O
2	IO_L29P_2	IO_L29P_2	N27	I/O
2	IO_L31N_2	IO_L31N_2	N29	I/O
2	IO_L31P_2	IO_L31P_2	N30	I/O
2	IO_L32N_2	IO_L32N_2	P21	I/O
2	IO_L32P_2	IO_L32P_2	P22	I/O
2	IO_L33N_2	IO_L33N_2	P24	I/O
2	IO_L33P_2	IO_L33P_2	P25	I/O
2	IO_L34N_2/VREF_2	IO_L34N_2/VREF_2	P28	VREF
2	IO_L34P_2	IO_L34P_2	P29	I/O
2	IO_L35N_2	IO_L35N_2	R21	I/O
2	IO_L35P_2	IO_L35P_2	R22	I/O
2	IO_L37N_2	IO_L37N_2	R23	I/O
2	IO_L37P_2	IO_L37P_2	R24	I/O
2	IO_L38N_2	IO_L38N_2	R25	I/O
2	IO_L38P_2	IO_L38P_2	R26	I/O
2	IO_L39N_2	IO_L39N_2	R27	I/O
2	IO_L39P_2	IO_L39P_2	R28	I/O
2	IO_L40N_2	IO_L40N_2	R29	I/O
2	IO_L40P_2/VREF_2	IO_L40P_2/VREF_2	R30	VREF
2	N.C. (◆)	IO_L41N_2	E27	I/O
2	N.C. (◆)	IO_L41P_2	F26	I/O
2	N.C. (◆)	IO_L45N_2	K28	I/O
2	N.C. (◆)	IO_L45P_2	K29	I/O
2	N.C. (◆)	IO_L46N_2	K21	I/O
2	N.C. (◆)	IO_L46P_2	L21	I/O
2	N.C. (◆)	IO_L47N_2	L23	I/O
2	N.C. (◆)	IO_L47P_2	L24	I/O
2	N.C. (◆)	IO_L50N_2	M29	I/O
2	N.C. (◆)	IO_L50P_2	M30	I/O
2	VCCO_2	VCCO_2	M20	VCCO
2	VCCO_2	VCCO_2	N20	VCCO
2	VCCO_2	VCCO_2	P20	VCCO
2	VCCO_2	VCCO_2	L22	VCCO
2	VCCO_2	VCCO_2	J24	VCCO
2	VCCO_2	VCCO_2	N24	VCCO
2	VCCO_2	VCCO_2	G26	VCCO
2	VCCO_2	VCCO_2	E28	VCCO

Table 110: **FG1156 Package Pinout *(Cont'd)***

Bank	XC3S4000 Pin Name	XC3S5000 Pin Name	FG1156 Pin Number	Type
2	IO_L19N_2	IO_L19N_2	M29	I/O
2	IO_L19P_2	IO_L19P_2	M30	I/O
2	IO_L20N_2	IO_L20N_2	M31	I/O
2	IO_L20P_2	IO_L20P_2	M32	I/O
2	IO_L21N_2	IO_L21N_2	M26	I/O
2	IO_L21P_2	IO_L21P_2	N25	I/O
2	IO_L22N_2	IO_L22N_2	N27	I/O
2	IO_L22P_2	IO_L22P_2	N28	I/O
2	IO_L23N_2/VREF_2	IO_L23N_2VREF_2	N31	VREF
2	IO_L23P_2	IO_L23P_2	N32	I/O
2	IO_L24N_2	IO_L24N_2	N24	I/O
2	IO_L24P_2	IO_L24P_2	P24	I/O
2	IO_L26N_2	IO_L26N_2	P29	I/O
2	IO_L26P_2	IO_L26P_2	P30	I/O
2	IO_L27N_2	IO_L27N_2	P31	I/O
2	IO_L27P_2	IO_L27P_2	P32	I/O
2	IO_L28N_2	IO_L28N_2	P33	I/O
2	IO_L28P_2	IO_L28P_2	P34	I/O
2	IO_L29N_2	IO_L29N_2	R24	I/O
2	IO_L29P_2	IO_L29P_2	R25	I/O
2	IO_L30N_2	IO_L30N_2	R28	I/O
2	IO_L30P_2	IO_L30P_2	R29	I/O
2	IO_L31N_2	IO_L31N_2	R31	I/O
2	IO_L31P_2	IO_L31P_2	R32	I/O
2	IO_L32N_2	IO_L32N_2	R33	I/O
2	IO_L32P_2	IO_L32P_2	R34	I/O
2	IO_L33N_2	IO_L33N_2	R26	I/O
2	IO_L33P_2	IO_L33P_2	T25	I/O
2	IO_L34N_2/VREF_2	IO_L34N_2/VREF_2	T28	VREF
2	IO_L34P_2	IO_L34P_2	T29	I/O
2	IO_L35N_2	IO_L35N_2	T32	I/O
2	IO_L35P_2	IO_L35P_2	T33	I/O
2	IO_L37N_2	IO_L37N_2	U27	I/O
2	IO_L37P_2	IO_L37P_2	U28	I/O
2	IO_L38N_2	IO_L38N_2	U29	I/O
2	IO_L38P_2	IO_L38P_2	U30	I/O
2	IO_L39N_2	IO_L39N_2	U31	I/O
2	IO_L39P_2	IO_L39P_2	U32	I/O
2	IO_L40N_2	IO_L40N_2	U33	I/O
2	IO_L40P_2/VREF_2	IO_L40P_2/VREF_2	U34	VREF

Table 110: **FG1156 Package Pinout *(Cont'd)***

Bank	XC3S4000 Pin Name	XC3S5000 Pin Name	FG1156 Pin Number	Type
N/A	VCCAUX	VCCAUX	Y5	VCCAUX
N/A	VCCINT	VCCINT	AA13	VCCINT
N/A	VCCINT	VCCINT	AA22	VCCINT
N/A	VCCINT	VCCINT	AB13	VCCINT
N/A	VCCINT	VCCINT	AB14	VCCINT
N/A	VCCINT	VCCINT	AB15	VCCINT
N/A	VCCINT	VCCINT	AB16	VCCINT
N/A	VCCINT	VCCINT	AB19	VCCINT
N/A	VCCINT	VCCINT	AB20	VCCINT
N/A	VCCINT	VCCINT	AB21	VCCINT
N/A	VCCINT	VCCINT	AB22	VCCINT
N/A	VCCINT	VCCINT	AC12	VCCINT
N/A	VCCINT	VCCINT	AC17	VCCINT
N/A	VCCINT	VCCINT	AC18	VCCINT
N/A	VCCINT	VCCINT	AC23	VCCINT
N/A	VCCINT	VCCINT	M12	VCCINT
N/A	VCCINT	VCCINT	M17	VCCINT
N/A	VCCINT	VCCINT	M18	VCCINT
N/A	VCCINT	VCCINT	M23	VCCINT
N/A	VCCINT	VCCINT	N13	VCCINT
N/A	VCCINT	VCCINT	N14	VCCINT
N/A	VCCINT	VCCINT	N15	VCCINT
N/A	VCCINT	VCCINT	N16	VCCINT
N/A	VCCINT	VCCINT	N19	VCCINT
N/A	VCCINT	VCCINT	N20	VCCINT
N/A	VCCINT	VCCINT	N21	VCCINT
N/A	VCCINT	VCCINT	N22	VCCINT
N/A	VCCINT	VCCINT	P13	VCCINT
N/A	VCCINT	VCCINT	P22	VCCINT
N/A	VCCINT	VCCINT	R13	VCCINT
N/A	VCCINT	VCCINT	R22	VCCINT
N/A	VCCINT	VCCINT	T13	VCCINT
N/A	VCCINT	VCCINT	T22	VCCINT
N/A	VCCINT	VCCINT	U12	VCCINT
N/A	VCCINT	VCCINT	U23	VCCINT
N/A	VCCINT	VCCINT	V12	VCCINT
N/A	VCCINT	VCCINT	V23	VCCINT
N/A	VCCINT	VCCINT	W13	VCCINT
N/A	VCCINT	VCCINT	W22	VCCINT
N/A	VCCINT	VCCINT	Y13	VCCINT